

OL-NVT4556UK

wafer level chip-scale package, 12 terminals, 0.4 mm pitch,
1.205 mm x 1.605 mm x 0.272 mm body

7 June 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	22-04-2014
Manufacturer package code	WLCSP12

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.59	1.605	1.62	mm
package width	1.19	1.205	1.22	mm
seated height	0.352	0.382	0.412	mm
package height	0.257	0.272	0.287	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	12	-	



2 Package outline

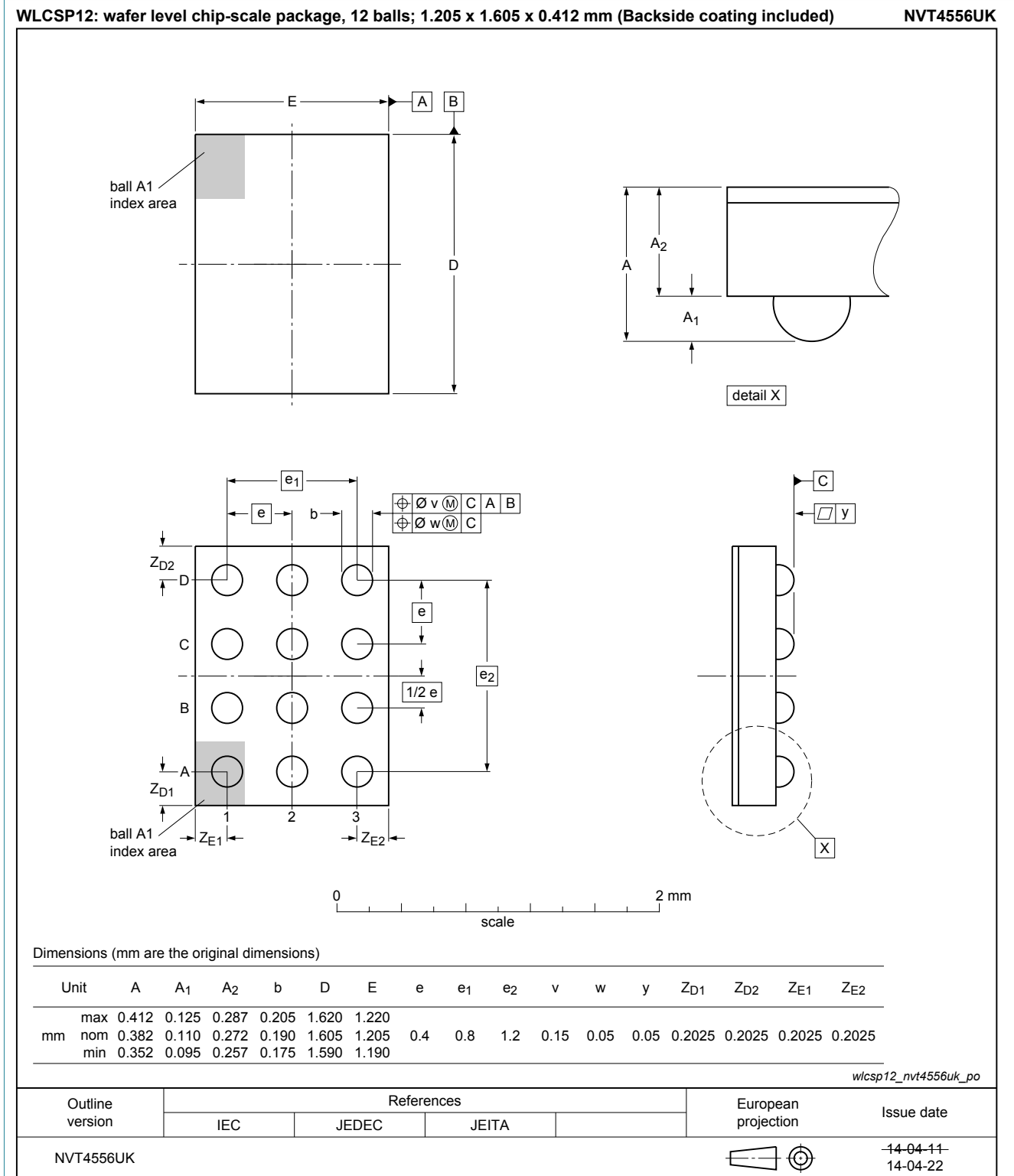


Figure 1. Package outline WLCSP12 NVT4556UK

3 Legal information

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